Direct Measurement of Coherency Limits for Strain Relaxation in Heteroepitaxial Core/Shell Nanowires

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Supporting Information

ABSTRACT: The growth of heteroepitaxially strained semiconductors at the nanoscale enables tailoring of material properties for enhanced device performance. For core/shell nanowires (NWs), theoretical predictions of the coherency limits and the implications they carry remain uncertain without proper identification of the mechanisms by which strains relax. We present here for the Ge/Si core/shell NW system the first experimental measurement of critical shell thickness for strain relaxation in a semiconductor NW heterostructure and the identification of the relaxation mechanisms. Axial and tangential strain relief is initiated by the formation of periodic a/2 ⟨110⟩ perfect dislocations via nucleation and glide on {111} slip-planes. Glide of dislocation segments is directly confirmed by real-time in situ transmission electron microscope observations and by dislocation dynamics simulations. Further shell growth leads to roughening and grain formation which provides additional strain relief. As a consequence of core/shell strain sharing in NWs, a 16 nm radius Ge NW with a 3 nm Si shell is shown to accommodate 3% coherent strain at equilibrium, a factor of 3 increase over the 1 nm equilibrium critical thickness for planar Si/Ge heteroepitaxial growth.

KEYWORDS: Heterostructure, core/shell, nanowire, critical thickness, germanium, silicon

Advanced device architectures for electronic and optoelectronic applications often require heterostructures to optimize performance.1−9 Strain engineering in these heterostructures has proven to be a critical strategy in tailoring the energy band-edge properties for enhanced charge carrier transport10,11 and photoemission properties.12 In current planar technology essentially all high performance Si-based microprocessors and III−V semiconductor lasers incorporate strain to enhance their performance. Dislocation-free heterostructures, however, cannot be grown with arbitrary thickness before the strain energy in the structure exceeds that required to form dislocations and defects in the grown layer, which in turn degrade its properties.13 To increase this critical thickness to be more useful for device applications, it is of interest to grow on compliant substrates or on 3-dimensional structures where the

Received: June 14, 2012
Revised: September 25, 2012
Figure 1. (a) Schematic diagram illustrating the different stresses existing in a core/shell NW: $\sigma_{zz}$, axial stress, $\sigma_{rr}$, radial stress, and $\sigma_{\theta\theta}$, tangential stress. (b) Schematic diagram depicting axial strain relief with a Frank partial dislocation at the interface with Burgers vector $b_{zz} = a/3 \langle 111 \rangle$. The effect of this dislocation is the appearance of an extra (111) plane in the Si shell along a single cross-section of the wire. (c) Schematic diagram depicting axial strain relief from a Burgers vector $b = a/2 \langle 011 \rangle$. The projection of this Burgers’s vector along the growth axis is $b'_z = a/3 \langle 111 \rangle$, resulting in the same formation of an extra (111) plane in the Si shell with respect to the core via bond shifting at the interface. Atomic arrangement (d) for a partial dislocation segment and (e) for a perfect dislocation segment. (f–i) Same magnification HRTEM images of a 15 nm radius Ge core.
misfit strain can be shared between the heterostructured layers.\textsuperscript{16} 

Semiconductor core/shell nanowires (NWs) offer an ideal platform for such heterostructuring where the small NW core diameters\textsuperscript{15} provide the required “substrate” compliance and where heterointerfaces are abrupt.\textsuperscript{16} However, 10 years after the first demonstration of core/shell NW growth,\textsuperscript{16} there is still no experimental quantification of their critical dimensions and
no clear identification of the mechanisms by which they relax, despite a number of theoretical predictions\textsuperscript{17–21} on their coherency limits. This contrasts to strained-layer growth on planar substrates where mechanisms and critical dimensions are well-established.\textsuperscript{22} Here using Ge/Si core/shell NWs, we provide: (i) the first experimental measurement of the critical thicknesses for strain relief via dislocations, (ii) the operative strain relaxation mechanism by observing periodically spaced a/2 \(110\) perfect dislocation loop segments in a single NW, (iii) dislocation dynamics simulations describing the dislocation segment nucleation and propagation on faceted core/shell NWs, and (iv) in situ transmission electron microscope (TEM) observation of the thermally induced dislocation segment glide in core/shell NWs.

In a heteroepitaxial core/shell cylindrical system, there exist three different stresses at the heterointerface (Figure 1a): (i) along the axis of the NW, \(\sigma_{zz}\) (ii) along the radius of the NW, \(\sigma_r\) and (iii) along the tangential direction to the NW, \(\sigma_{\theta\theta}\). Previous works have considered Frank-type dislocations (Figure 1b,d) as one possible source of strain relief in core/shell NWs.\textsuperscript{17–21} There are many examples of pure edge dislocations detected in NW heterostructures.\textsuperscript{23–25} However, such dislocations are unlikely to form by low energy glide processes, at least at the typical growth and annealing temperatures (<600 °C) for our core/shell NWs. Their Burgers vectors do not sit on a low energy glissile plane, and thus, propagation by glide is energetically unfavorable. In contrast, perfect dislocations (Figure 1c,e), which form by loop nucleation and glide on one of the \{111\} slip planes, can be formed at our growth temperatures (∼500 °C). Reactions of two such dislocations have been used to explain the existence of these sessile dislocation segments.\textsuperscript{26} Here, we will establish the nature of the dislocation formation as the coherency limit is reached.

Our experimental approach consisted of growing \{111\} oriented Ge NW cores by chemical vapor deposition through the vapor—liquid—solid growth mechanism with subsequent in situ Si shell deposition.\textsuperscript{27} The Ge NW core radii were 15 nm, and the Si shell thickness was varied from 1 to 10 nm (see Figure 1). Postannealing at 600 °C was carried out for evaluation of the equilibrium critical thickness. As the shell thickness increases to 2.7 nm (Figure 1f), we generally found perfect coherent epitaxial core/shell structures without defects. At a thickness of 3.2 nm (Figure 1g) up to 5 nm (Figure 1h), we began to observe additional strain relieving Si \{111\} planes with respect to the Ge core, along the growth axis of the NW that had a projected component of the Burgers vector of a/3\{111\} \((b'_c\text{ in Figure 1b})\). The average axial separation of these additional planes was 26 (111) bilayers or 8.5 nm. From basic elasticity theory, the linear density of dislocations necessary to relieve stress in the axial direction is \(\rho = f/\ell b\cos(\theta)\), where \(\ell b\) is the magnitude of the dislocation Burgers vector projected on the plane of the heterointerface, \(\theta\) is the angle between the Burgers vector and the growth orientation, and \(f = 0.0419\) is the lattice mismatch of Si with respect to Ge. For a perfect dislocation, perpendicular to the \{111\} NW axis, with an a/2 \(110\) Burgers vector component projected on the \{111\} growth orientation equal to \(b'_c\), this results in an axial dislocation separation distance, \(s = 1/\rho = 7.5\) nm, 12% less but consistent with our observed dislocation spacing (8.5 nm) accounting for partial relaxation of the \(\sigma_{zz}\) and \(\sigma_{\theta\theta}\) strains. From Figure 1, we conclude that the equilibrium critical Si shell thickness is 3 nm for a 15 nm Ge core radius which significantly exceeds that of bulk heteroepitaxy (1 nm). It is expected that additional reduction in the Ge NW core radius can further increase the equilibrium critical thickness.\textsuperscript{17–21}

For \{111\} oriented NWs, there are three \{111\} slip planes (((1T), (11T), (11T)) at angles of 19.5 ° from the growth axis. When Ge/Si NWs are viewed along a \{110\} zone axis in the TEM, a/2 \{110\} dislocation segments in the Si shell on one of these slip planes should be observable. A dislocation could nucleate on one edge of the NW and move in its slip plane by glide to deposit a misfit line at the Si/Ge interface. Figure 2 shows several instances of these dislocations that nucleate on one surface of the Si shell and glide on the (111) plane. Dislocations of the same type could successively nucleate on three adjacent facets leading to a complete loop formation around the NW core. For a 16 nm NW radius, the axial loop length is 32/tan(19.5 °) nm = 90 nm, consistent with the 88 nm observed experimentally in Figure 2. Interestingly, five such dislocation loops could be traced from one surface of the NW along the (11T) plane to the other surface (Figure 2). It is also evident from the magnified images in Figure 2 that these are perfect dislocation segments. In addition, in all growths and TEM characterization of this study, we never observed extra Si planes on both surfaces of the Si shell on the same \{111\} plane orthogonal to the growth direction (see Figure 1i)), which further confirms that these dislocations are not Frank dislocations. Thus, these observations show that the strain relieving mechanism for loss of coherency in \{111\} oriented Ge/Si core/shell NWs is by dislocation glide on the inclined \{111\} planes.

To further elucidate the formation and propagation mechanism of perfect dislocations by glide and to identify the preferred nucleation sites and dislocation line directions, we first analyzed the heteroepitaxial stress field in a simplified \{111\} oriented Ge/Si core/shell NW geometry with \{112\} or \{110\} side facets. The core radius and the shell thickness were set equal to 32 and 6 nm, to exceed the measured critical thickness. In Figure 3a and b, we plot the resolved shear stress (RSS), calculated by the finite element method, for a dislocation with \{111\} slip plane and \(b = a_{110}/2\) \{110\} Burgers vector, in a NW with \{112\} and \{110\} side facets, respectively. A large positive value of the RSS indicates a preferred site for dislocation nucleation and propagation. On the contrary, in case of zero or negative RSS the propagation of the same dislocation is hindered. By inspecting the RSS map in Figure 3 we expect dislocations to nucleate at the NW corners where the RSS is maximum and to propagate in the Si shell volume where the RSS is positive.

To support this analysis, dislocation dynamics (DD) simulations\textsuperscript{28,29} were performed in the two NW configurations described above. In Figure 3e ((112 facets case) and Figure 3f ((110) facets case) we show two snapshots from the simulations obtained by considering dislocations with \{111\} slip plane and \(b = a_{110}/2\) \{110\} Burgers vector in agreement with the RSS analysis and prior experimental observations,\textsuperscript{30} we found that the nucleation of dislocations is preferential to the NW corners, as shown in Figure 3e where a small new loop is located at the NW edge position. Moreover, dislocations evolve from the NW corners in their slip plane, sweeping across the area in the Si shell where the RSS is positive, and depositing a misfit line at the Ge/Si interface. As a consequence, we observed some straight dislocation lines crossing a single NW facet, as in Figure 3f, or dislocation segments that cross a NW corner depositing a misfit line on two adjacent facets, as in...
Figure 3e. Dislocation lines perpendicular to the NW growth axis, as shown in Figure 3e, have a projected component of the Burgers vector $b_z' = a/3[111]$, and the position of the extra half-plane in the Si shell connected with such dislocation geometry is aligned to the [211] direction, in excellent agreement with the experimental observations. These dislocation segments will relieve the maximum axial strain, while the oblique segments can relax the tangential strain. Dislocation evolution in the other slip planes $\{11\bar{1}\}$ and $\{111\}$ (not shown) led to similar dislocation line arrangements in the adjacent NW facets, that contribute to axial and tangential strain relaxation in the whole Si volume. Moreover, no propagation of loops in the basal (111) plane was ever observed, as for Frank-type dislocations, according to RSS predictions. These results corroborates the experimental findings of gliding dislocations observed in Figures 1 and 2 and shed light on their nucleation sites, propagation, and termination in the Si volume.

Our in situ grown single crystal core/shell NWs already show dislocation segments in the as-grown NWs with Si shell thicknesses above 3 nm, even without postannealing. The 600 °C annealing step allowed us to observe the periodicity of these dislocations as shown in Figures 1 and 2. To further confirm dislocation glide on the (11T) planes, we performed in situ TEM experiments on as-grown NWs where the temperature of the TEM stage was ramped (5 °C/s) to 450 °C, paused for 30 min, and then ramped to 600 °C. Careful inspection of video frames taken during the annealing experiments showed that dislocation movement and glide occurs on the (11T) planes.

Figure 4a−d shows HRTEM snapshots at a short incremental time with two reference points marked by arrows on the images a−d: a thin red arrow for a dislocation with small insertion of an extra (111) plane in the Si shell, and a blue arrow at the corner of the carbon-coated portion of the NW to reference the relative position along the NW. The scale bar is 5 nm. Time, $t$, is given in each frame in min:s. (e) Inverse FFT of the image in c showing contrast from both (111) and (11T) planes. (f) Geometrical relationship for expansion of the extra Si (111) plane during gliding on the (11T) slip plane.
with the expected value from Figure 4f. The glide velocity during the motion of these dislocations is 0.13 nm/s which is $10^4$ times slower than the glide velocity in Si$_{0.77}$Ge$_{0.23}$/Si thin film heterostructures at the same temperature,$^{31}$ enabling us to observe and accurately measure dislocation extension at a subnanometer scale.

The discussion above points to a critical thickness in core-shell NWs to partially relieve strain. Cross-sectional HRTEM (Figure 5a) for a Si shell thickness $>3$ nm showed extra (111) planes along the cross-section of the nanowire. Dislocation segments on all three slip planes lead to extra (111) planes in the Si shell that can be observed only when looking at an axial cross-section of the heterostructured NW as is the case in Figure 5a. The resulting extra Si (111) planes in the cross-section of the heterostructured NW allows for tangential strain relief along the circumference of the NW.

As the Si shell thickness increases to 8 nm on a 15 nm Ge core radius (Figure 5b), we start to observe additional strain-relieving mechanisms. Figure 5c and 5d show roughening and twin boundary formation (Figure 5c) in addition to the perfect dislocation segments (Figure 5c). Tilt twin boundaries in the thick Si shells can result from rearrangement of excess dislocation segments as the Si shell layer thickness increases and roughens, which in turn helps in relieving residual axial and tangential strain not relieved by the perfect dislocations discussed above. The analysis of axial strain based on FFT patterns from Figure 5b indicates essentially full axial strain relief, whereas similar analysis for shell thicknesses in the range of 1–4 nm gave up to $\sim3\%$ residual axial strain even with the insertion of the perfect dislocation segments, which corroborates with the RSS analysis discussed in Figure 3.

The present results for thicker shells are consistent with earlier core/shell NW studies. In our case, high quality core–shell growth is enabled by a procedure that we devised to engineer a Si blocking interface between the Au seed and the Ge NW sidewalls.$^{32}$ This approach leads to the elimination of Au diffusion during the synthesis of single-crystal Ge/Si core/shell NW heterostructures which enhances early roughening during shell growth. The present growth sequence enables a better assessment of coherency limits and relaxation mechanisms in core/shell NWs. In contrast to earlier reports on strain relaxation in Ge/Si core/shell NWs, where ex-situ Au etching was performed prior to the epitaxial growth of the Si shells at higher temperatures than those used here,$^{23}$ strain relaxation via island growth was not observed in our experiments. For [110] oriented NWs, indications of $a/2[110]$ dislocation loops were observed,$^{33}$ which is consistent with our findings for misfit strain relaxation, and which we also find to be the case upon close examination of the TEM images of the first report on synthesis of Ge/Si core/shell NWs.$^{16}$ Rotation in FFT patterns of a Ge/Si HRTEM image in a recent report indicates twin and grain boundary formation when the Si shells becomes sufficiently thick,$^{34}$ which is in accordance with our observations for thick Si shells. It is worth noting that the Ge/Si material system provides a simpler platform for studying strain relief in core/shell heterostructured NWs when compared to III/V counterparts, where it has been observed that shell growth in such systems depends on the polarity of the faceted surfaces. This effect can lead, for example, to shell thicknesses that are not uniform across the cross-section of a single InAs/GaAs core/shell structures.$^{35}$

These observations provide a framework for understanding strain relaxation in 3-dimensional nanostructures. In particular, we have identified the coherency limits for core/shell NWs for the first time and determined the operational dislocation glide mechanism which limits coherency. For some material systems such as III–V NWs, the perfect dislocation loop segments can lead to different magnitudes of axial and radial strain relief, where it becomes conceivable to tailor axial and tangential stresses separately. The implication of such strain engineering would, for example, allow tailoring the stress components along a transistor’s channel length, when made on a heterostructured core/shell NW, for separate tuning of electron and hole mobilities. Also, thicknesses of shells must be carefully controlled since increasing strain can enhance mobility while maintaining thin shell thicknesses to achieve high gate capacitance and therefore high transistor drive currents and switching speeds.

**Experimental Section.** Ge NWs were grown on Ge (111) surfaces in a cold wall CVD system using 30 nm diameter Au colloids according to the preparation and two-step growth (90 s nucleation step at 360°C followed by quick ramp to 276°C) procedures, as described elsewhere.$^{36}$ After the NW elongation step at 276°C in GeH$_4$ (30% in H$_2$) and GeH$_4$ partial pressure, $P_{\text{GeH}_4}=0.6$ Torr, a SiH$_4$ (50% in H$_2$) flow was implemented for 15–30 min ($P_{\text{SiH}_4}=1.75$ Torr) to deposit a Si interfacial barrier.

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**Figure 5.** (a) Axial HRTEM cross-section of a Ge/Si core/shell NW with a 3.5 nm thick Si shell viewed from slightly off a NW (111) growth axis ([332] zone view) showing semiperiodic extra (111) planes in the Si shell with an average spacing of 8 nm. (b) HRTEM sideview cross sections of a Ge/Si core/shell NW with $r_g=15$ nm and $r_e=23$ nm (8 nm shell thickness) showing an onset of a roughened Si shell on the Ge NW. Higher magnification images showing in c the existence of perfect dislocation loops and (d) formation of twin boundaries.

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dx.doi.org/10.1021/nn3022434 | Nano Lett. XXXX, XXX, XXX–XXX
layer underneath Au, whose thickness was on the order of the NW diameter. SiH₄ was then introduced, and the temperature was ramped up to 500 °C where the i-Si shell deposition took place at $P_{\text{SiH}_4} = 0.25$ Torr with a total ramp and deposition times of 17–53 min. The grown samples were annealed at 600 °C in a rapid thermal annealing system for 30 min under forming gas (15% H₂ in N₂).

For transmission electron microscopy (TEM), the as-grown NWs were suspended in an isopropanol solution and deposited on lacey carbon TEM grids. Investigations were carried out with TEM with a field emission electron source operating at an accelerating voltage of 300 kV. The in situ TEM studies were performed with a heating stage capable of heating up to 1000 °C. For cross-sectional TEM, the NWs were transferred directly from the growth substrate by dry transfer onto a 50 µm thick fluoropolymer embedding film. The fluoropolymer film was then embedded into an Araldite based epoxy resin, and the whole structure was cut into 50–70 nm slices using a diamond ultramicrotome knife and transferred onto Cu grids for imaging.

**Simulations.** The epitaxial stress field in (111) oriented Ge/Si core/shell NWs with (112) or (110) side facets was calculated using isotropic linear elasticity theory solved by the finite element method (FEM). The resolved shear stress (RSS) was calculated for different slip systems pertaining to the Burgers vector of each dislocation type, or for modeling dislocations driven by external edge forces. A line-tension expression to mimic the force acting on segments touching the free surfaces was used. Finally, the dynamics were solved by taking into account these two contributions and the stress field arising from all the dislocations in the NW volume. In the DD simulations presented here, dislocation loops with 4 nm radii are periodically introduced at random positions in the Si shell, similar to ref 40. If the stress field at these positions promotes loop expansion, they will evolve with time and contribute to the NW strain relaxation.

### Acknowledgments
This work was performed, in part, at the Center for Integrated Nanotechnologies, a U.S. Department of Energy, Office of Basic Energy Sciences user facility at Los Alamos National Laboratory (Contract DE-AC52-06NA25396) and Sandia National Laboratories (Contract DE-AC04-94AL85000). This work is funded in part by the Laboratory Directed Research and Development (LDRD) program at Los Alamos National Laboratory.

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### Notes
The authors declare no competing financial interest.


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